IPC ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IDC Wah Site for Information on IDC 1752 Standard Form Tyr				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier	Information														
Company name* Comp			Company un	Company unique ID			Unique ID Authority				Resp	Response Date*			
nsemi												2024-05-09			
ontact Na	ame		Title - Contact]	Phone - Contact*				Ema	Email - Contact*			
Product-E	nv-Stewards		Product Envi	Product Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Repre	Title - Representative			Phone - Representative*			Emai	Email - Representative*					
Product-E	nv-Stewards	Product Enviro Compliance				NA			Proc	Product-Env-Stewards@onsemi.com					
	Requester Item Number	Mfr Iten	n Number Mfr Item Name				Effective Dat	Date Version N		Manufacturing Site		Weig	Weight* UOM	UOM	Unit Type
		GBPC2502W BR G		BR GBPCW GP	BR GBPCW GPPN 25A 200V		2024-05-09		TSCI		SCBE		16949.998 mg		Each
Ianufac	eturing Proccess Informa	tion												1	1
,	Terminal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	L Rating Peak P		cess Body Temperature M		re Max Time	x Time at Peak Temperat		e Number of Reflow Cycles		cles
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy NA		NA		0		С	30	se	conds	3		
omments			·		·			·		· ·	· ·				
	nformation regarding material														

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	2949.3	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		589.8748	mg
			Supplier	Silica (SiO2)	14464-46-1		2064.5603	mg
			Supplier	Phosphorus (P)	7723-14-0		58.9152	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		235.9497	mg
Die	33.561	mg	Supplier	Silicon (Si)	7440-21-3		30.2049	mg
			В	Nickel (Ni)	7440-02-0		0.2181	mg
			Supplier	Gold (Au)	7440-57-5		0.0503	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	3.0876	mg
Die Attach Solder	18.1365	mg	Supplier	Silver (Ag)	7440-22-4		0.4534	mg
2001			A	Lead (Pb)	7439-92-1	7a	16.7763	mg
			Supplier	Tin (Sn)	7440-31-5		0.9068	mg
Die Attach Solder - Solder Wafer	82.8855	mg	Supplier	Silver (Ag)	7440-22-4		2.0721	mg
			A	Lead (Pb)	7439-92-1		76.6691	mg
			Supplier	Tin (Sn)	7440-31-5		4.1443	mg
Heat Sink	3803.24	mg	Supplier	Aluminum (Al)	7429-90-5		3803.24	mg
Lead Frame	1220.4	mg	Supplier	Iron (Fe)	7439-89-6		0.9763	mg
			Supplier	Copper (Cu)	7440-50-8		1219.1797	mg
			Supplier	Phosphorus (P)	7723-14-0		0.244	mg
Marking Ink	0.5085	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.0254	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.0254	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.0509	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.3305	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0763	mg
Mold Compound-White	6552.36	mg		Polymer Resin	proprietary data		1092.2784	mg
			Supplier	1,2-Bis(pentabromophenyl) ethane	84852-53-9		382.0026	mg
			Supplier	Brominated epoxy resin	Proprietary Data		1419.8964	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		218.1936	mg
			Supplier	Carbon Black (C)	1333-86-4		54.3846	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		655.236	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2730.3682	mg
Plating-2	14.916	mg	В	Nickel (Ni)	7440-02-0		14.916	mg
Terminal	2274.69	mg	Supplier	Iron (Fe)	7439-89-6		2.7296	mg

	Supplier	Copper (Cu)	7440-50-8	2270.9822	mg
	Supplier	Phosphorus (P)	7723-14-0	0.9781	mg